Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.013”**

**ANODE**

**.0095 x .0095”**

**.013”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .0095” X .0095”**

**Backside Potential: Cathode**

**Mask Ref: CPZ28**

**APPROVED BY: DK DIE SIZE .013” X .013” DATE: 8/31/21**

**MFG: CENTRAL SEMI THICKNESS .0075” P/N: 1N755A**

**DG 10.1.2**

#### Rev B, 7/19/02